

STM32WL3 - QFN48 - 2-Layers - IPD

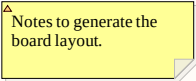
MB2176

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- Sheet 2: Top
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- Sheet 4: Supply
- Sheet 5 : RF front-end

Legend

- General comment such as function title, configuration, ...
- Text to be added to silkscreen.
- Warning text.



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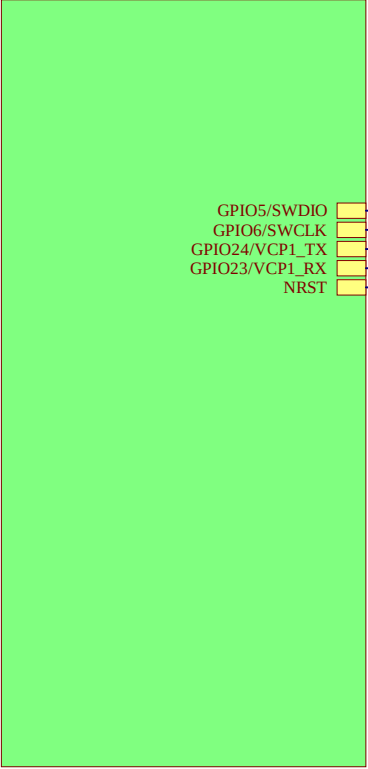
U_Top
Top.SchDoc



Title: Project Overview		
Project: STM32WL3 - QFN48 - 2-Layers - IPD		
Variant: 868_16dBm		
Revision: A-01		Reference: MB2176
Size: A4	Date: 26/03/2025	Sheet: 1 of 5

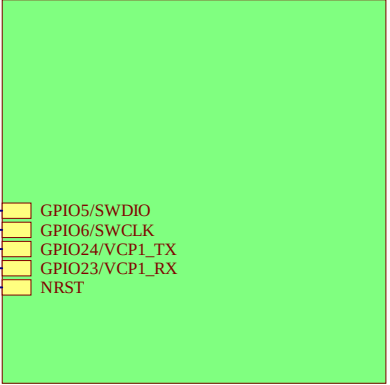


Designator
MCU_IOs.SchDoc



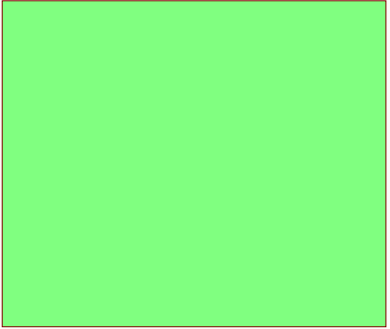
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GPIO6/SWCLK
GPIO24/VCP1_TX
GPIO23/VCP1_RX
NRST

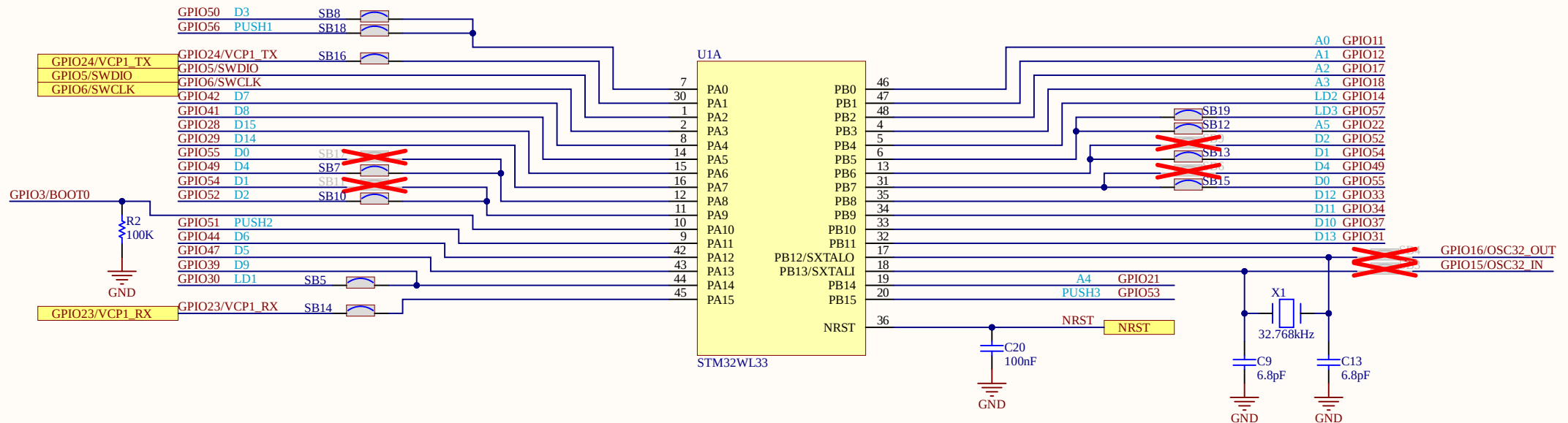
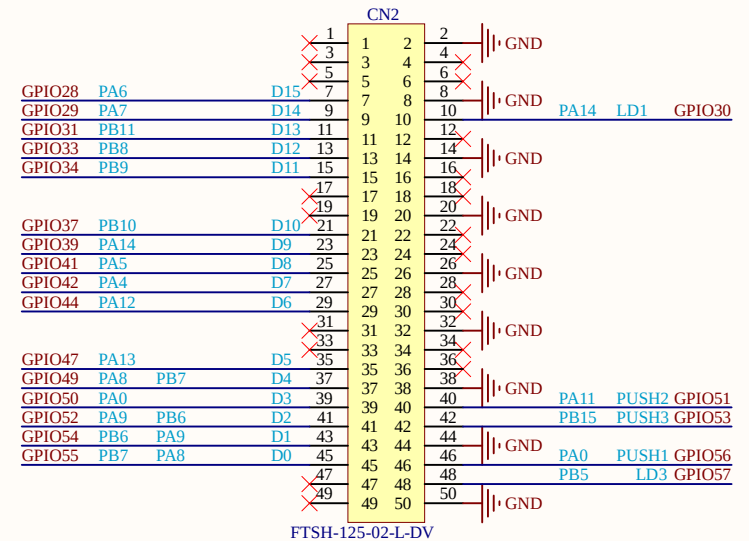
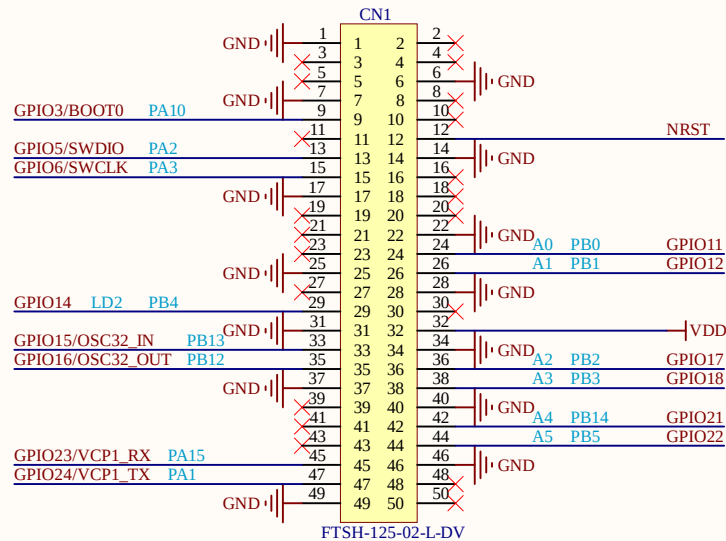
Designator
Supply.SchDoc

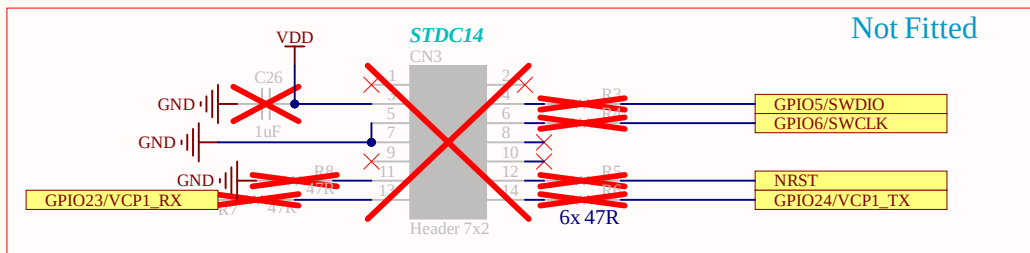
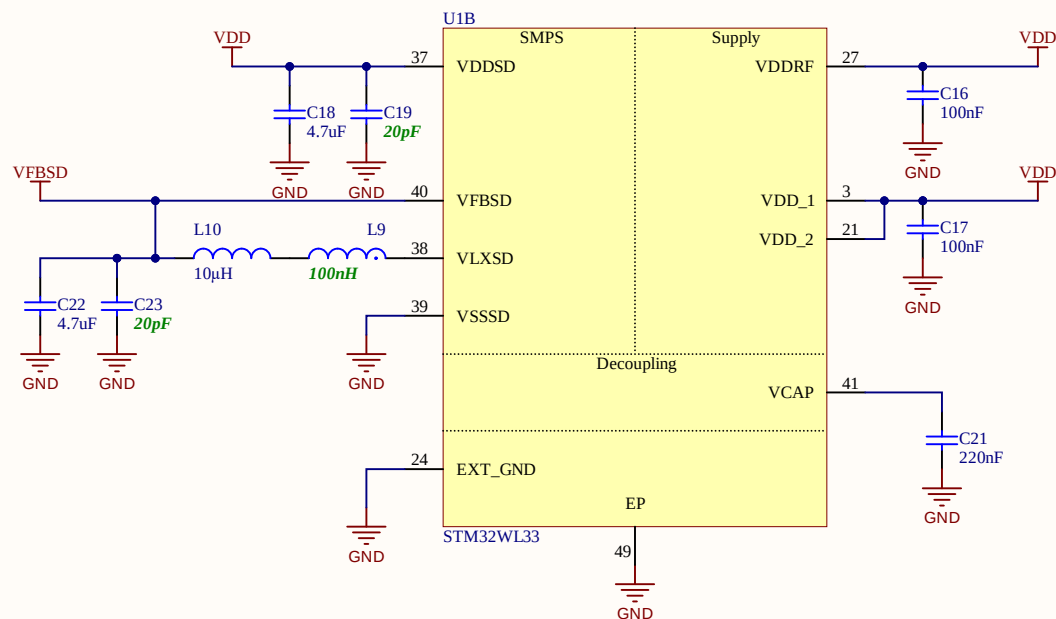


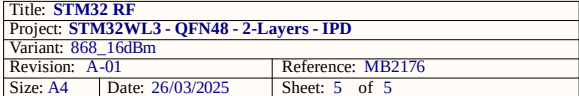
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GPIO6/SWCLK
GPIO24/VCP1_TX
GPIO23/VCP1_RX
NRST

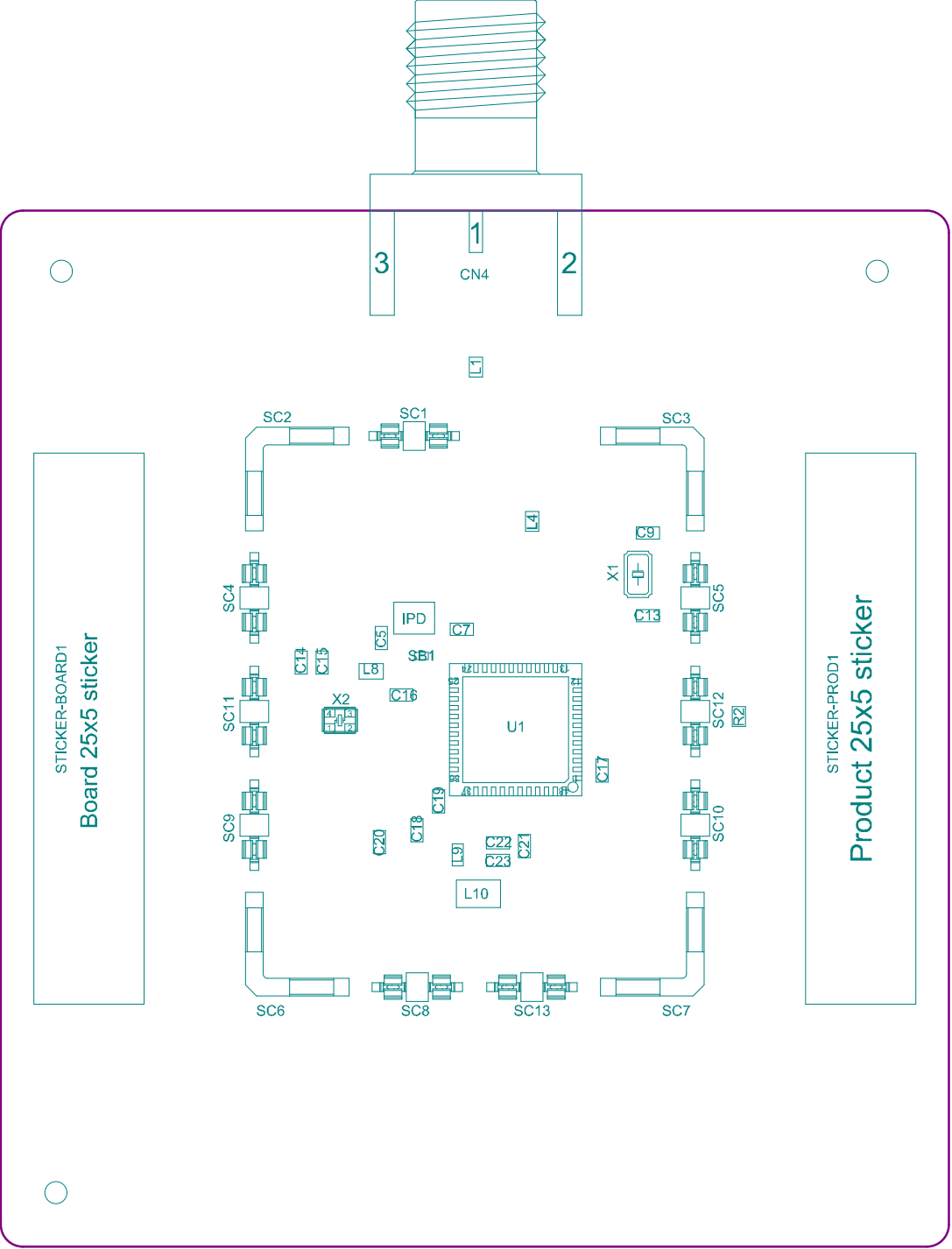
Designator
RF.SchDoc











Project: STM32WL3 - QFN48 - 2-Layers - IPD

Layer: M14-Top Assembly

Variant: 868_16dBm

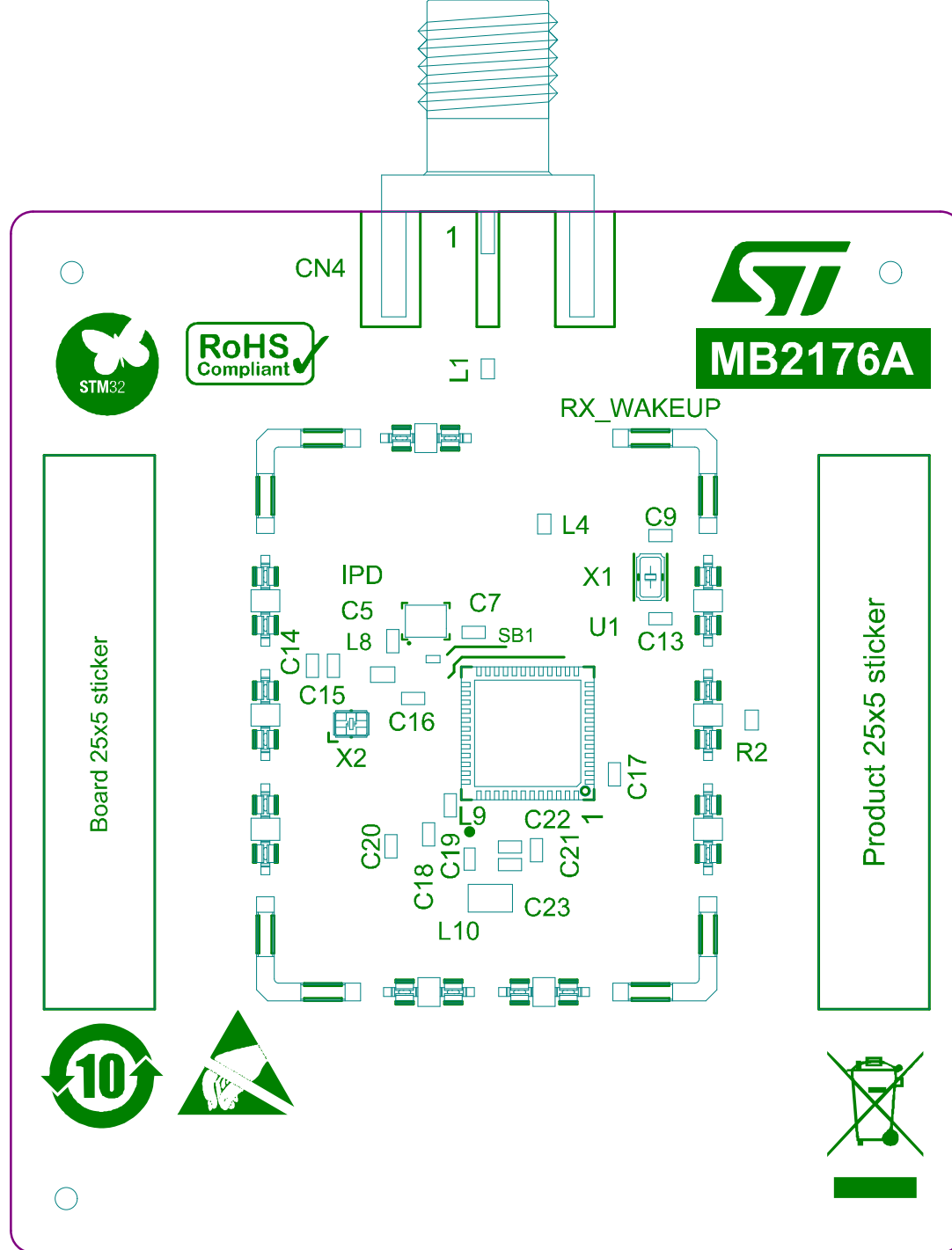
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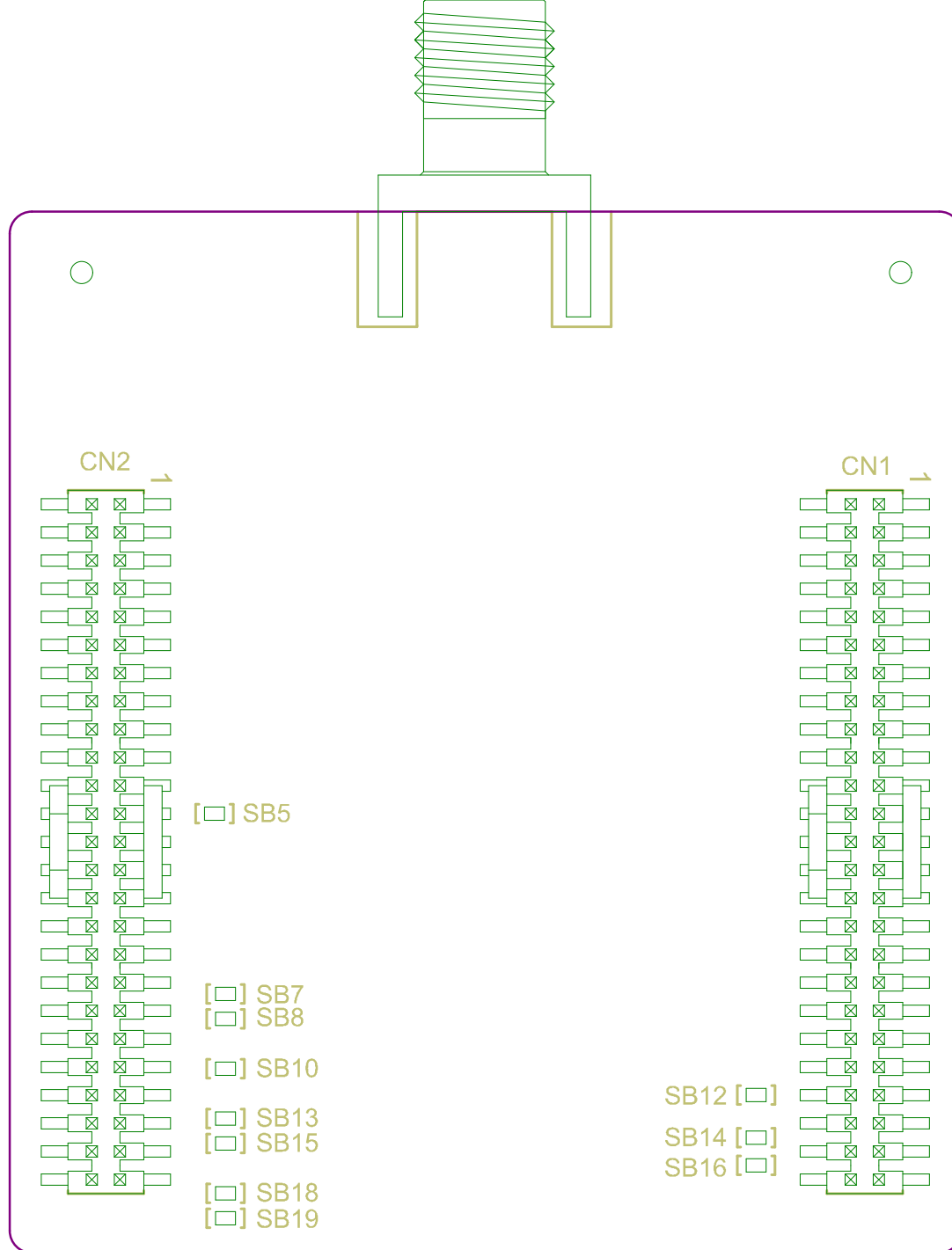
Gerber: .GM14

Ref: MB2176

Rev: A







Bottom Overlay

.GBO